

参考基板レイアウト (マウント面)
P.C.B. PATTERN LAYOUT (REF.) (MOUNT AREA)

- NOTES
- 材質
MATERIAL
ハウジング: ガラス入りPPS、黒色、UL94V-0
HOUSING: G.F.PPS, BLACK, UL94V-0
ターミナル: 銅合金 (t=0.32)
TERMINAL: COPPER ALLOY
 - メッキ仕様
PLATING
コンタクト部: 金メッキ 0.1μmMIN.
CONTACT AREA: Au 0.1μmMIN.
テール部: 金メッキ 0.1μmMIN.
TAIL AREA: Au 0.1μmMIN.
下地メッキ: ニッケルメッキ 1.0μmMIN.
UNDER-PLATING: NICKEL 1.0μmMIN.
 - 嵌合相手: 52465, 52588 シリーズ
MATES WITH 52465, 52588 SERIES
ウェハのφから隣接するピンのφ迄の位置とする。
SHOW POSITION FROM φ OF WAFER TO φ OF ADJACENT PINS.

0.8	5.8	4.9	3.2	53307-1032	53307-1038	10	53307-**38
D	C	B	A	エンボス極包 EMBS PKG NO.	コネクタ単体 MATERIAL NO.	極数 CKT	MODEL NO.

RELEASED EC NO: J2007-2662 DR: N. HAYASHI 2007/05/09 CHK: K. KASAHARA 2007/05/11 APPR: N. UKITA 2007/05/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY H. YAJIMA	DATE 2007/03/20	TITLE 0.8 B/B CONN WAFER ASSY ST SMT -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY K. KASAHARA	DATE 2007/03/20	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2007/03/20	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-53307-022	SHEET NO. 1 OF 2
0	DESCRIPTION	ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			

10 9 8 7 6 5 4 3 2 1

F

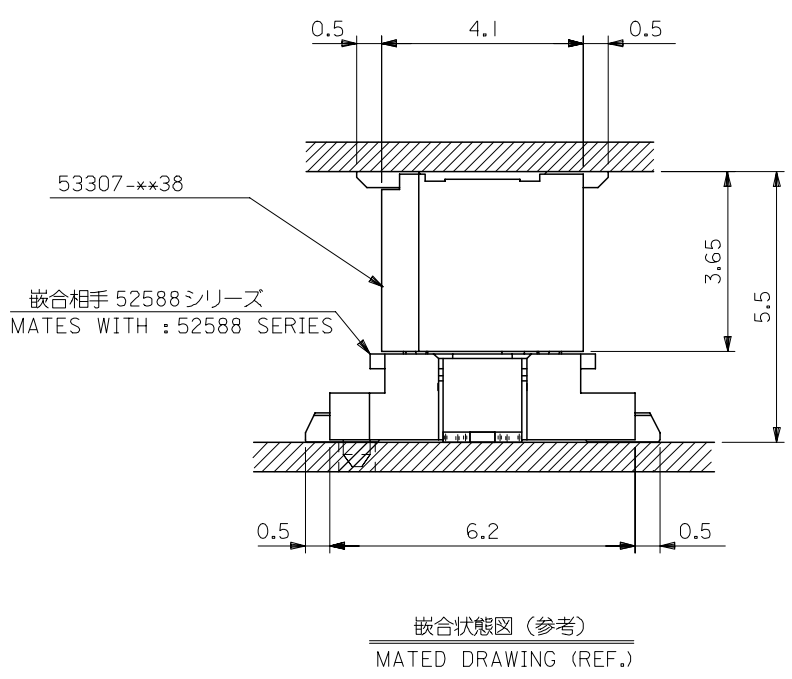
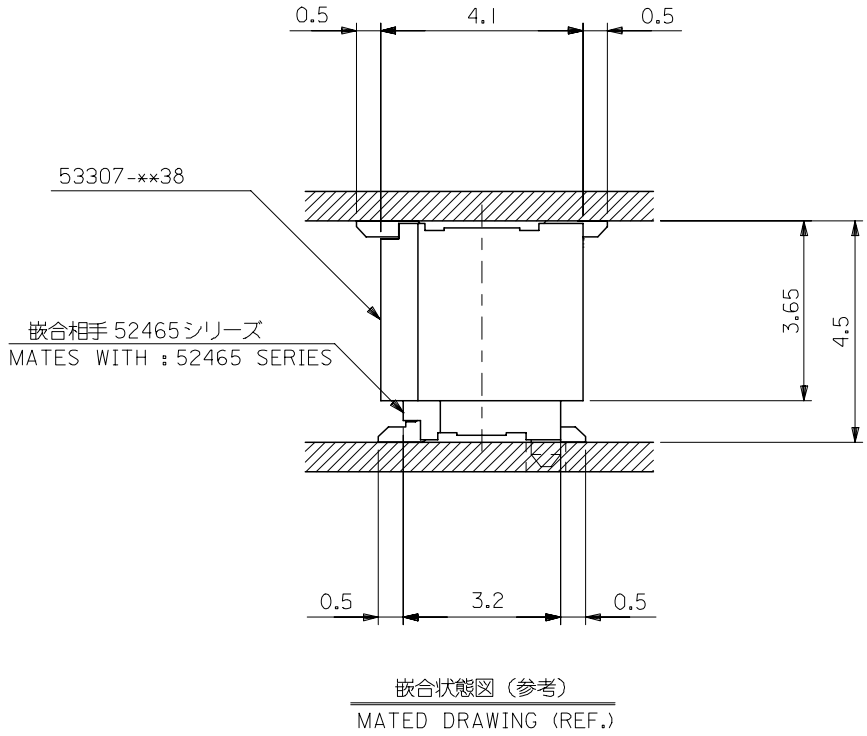
E

D

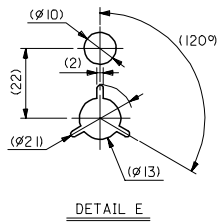
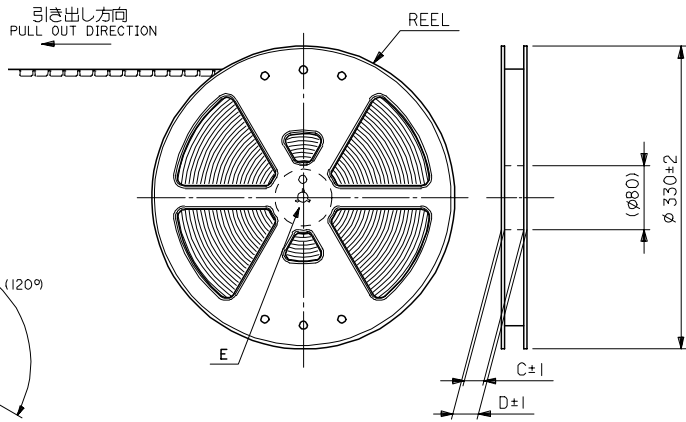
C

B

A

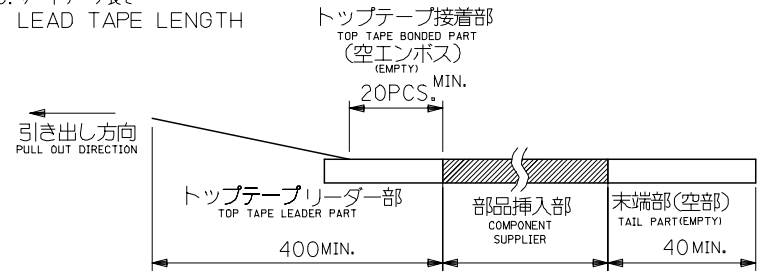


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	10 OVER 30 UNDER	±0.25	CHECKED BY K. KASAHARA		DATE 2007/03/20		MOLEX INCORPORATED DOCUMENT NO. SD-53307-022 SHEET NO. 2 OF 2	
	30 OVER	±0.3	APPROVED BY N. UKITA		DATE 2007/03/20			
	ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE SHEET 1 OF 2			
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



NOTES: 1. 製品詳細寸法については製品単体図面SD-53307-022を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING NO. SD-53307-022

- 2. 梱包数量: 1000/リール
THE NUMBER OF PACKAGED CONNECTORS : 1000 PIECES/REEL
- 3. リードテープ長さ
LEAD TAPE LENGTH



- 4. 材料
MATERIAL
キャリアテープ: ポリプロピレン (PP)
CARRIER TAPE : POLYPROPYLENE (PP)
トップテープ: PET, PE, PEF
TOP TAPE : PET, PE, PEF
リール: ポリスチレン (PP) <リサイクル材含む>
REEL : POLYSTYRENE (PP)
<RECYCLE MATERIAL CONTAINED>

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	10 ⁰ OVER 30 UNDER	± ---	CHECKED BY K. KASAHARA	DATE 2007/03/20				
	30 OVER	± ---	APPROVED BY N. UKITA	DATE 2007/03/20	MOLEX INCORPORATED			
	ANGULAR	±3 °	MATERIAL NO.	DOCUMENT NO.				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-53307-023		1 OF 2		

10 9 8 7 6 5 4 3 2 1

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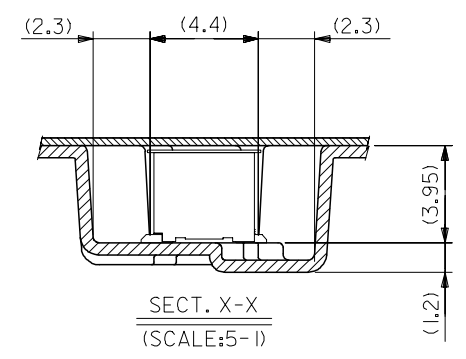
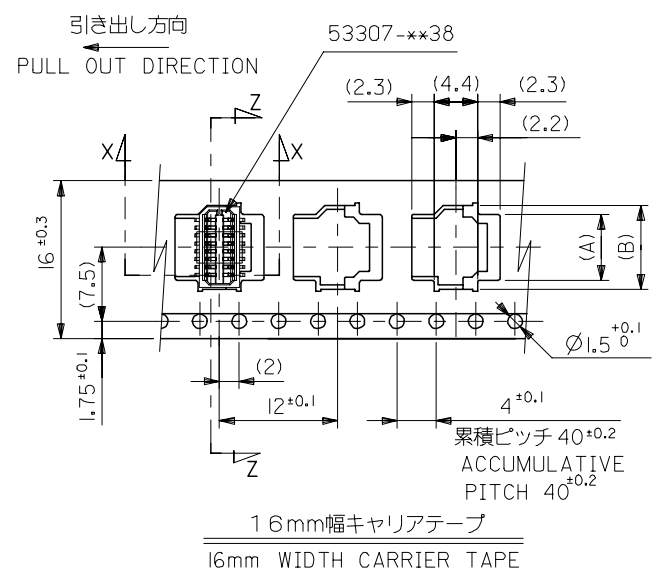
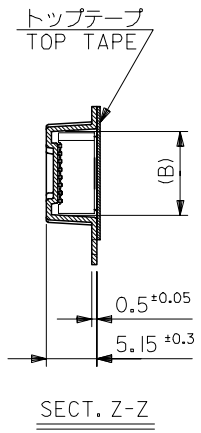
E E

D D

C C

B B

A A



16	21.4	17.4	6.1	4.3	53307-1038	53307-1032	10	53307-**32
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	(B)	(A)	コネクタ単体 CONNECTOR	エンボス梱包 MATERIAL NO.	極数 CKT	MODEL NO.

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	ANGULAR	±3 °						

9 8 7 6 5 4 3 2 EN-02JA(021)